Rzeczpospolita Polska

VIGO SYSTEM

Narodowe Centrum Badań i Rozwoju

ORDER DESCRIPTION

1. Object of the contract

The subject of the contract is Developer in the amount of:

- Developer „ready to use" - 1 piece, packaged in 5l bottle

2. Parametres

5.1 Detailed scope of the subject of the contract

Product name	Parameter	Specification
1. Developer	Properties	• Allows to reach steep sidewalls • 2.38 % TMAH in H_2O • Contains sufactants for quick and homogeneous wetting of the substrate • Contains additives to remove mask residues after development • Contains an ingredient which will attack slightly crosslinked resist, while more heavily crosslinked resist will be untouched • Compatible with negative resist
	Form of material	• Developer supplied in a single component form
	Packaging	• Developer supplied in a single 5 l bottle

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ORDER DESCRIPTION

1. Object of the contract

The subject of the contract is Chromium Etchant in the amount of:

- Chromium Etchant – 1 piece supplied in 5l bottle

2. Parametres

5.1 Detailed scope of the subject of the contract

Product name	Parameter	Specification
1. Chromium etchant	Properties	• Alkaline etchant for Cr • Allows to remove thin Cr layers with selectivity to metals like: Au, Sn, Pt, Cu, Ni, Ti, Ta • Use for semiconductor fabrication • Semiconductor materials: Si, SiO_2, Si_3N_4 • No attack metals: Au, Sn, Pt, Cu, Ni, Ti, Ta • Could be used for Cr barrier or adhesion layer in a plating seed stack • Increase of the etching rate by increased temperature up to 40°C • Resists: common Novolak as masking resist (e.g. AZ® Photoresist) • Low undercut (in the range of the layer thickness), minimum feature size < 1µm • Selectivity to many materials, e.g. common metals used in electroplating industry • The etching rate is around 10 – 15nm/min w at 40°C (accordingly lower at room temperature) • A sputtered 30nm Cr layer is etched in about 180 seconds • The mixed etching solution is stable over time and can be used multiple times on each application
	Form of material	• Chrome etcher supplied in a single component form
	Packaging	• Chrome etcher supplied in a single 5 l bottle

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ORDER DESCRIPTION

1. Object of the contract

The subject of the contract is Photoresist remover in the amount of:

- Remover ”ready to use” - 2 pieces supplied in 5l bottles

2. Parametres

5.1 Detailed scope of the subject of the contract

Product name	Parameter	Specification
1. Photoresist remover	Properties	• Negative and positive tone photoresist remover • Complete water miscibility • Compatible with most common substrate materials • Very high stripping rate: >10µm/min • Bath life up to 72h at 65°C • TMAH and Fluoride • Hydroxylamine free
	Form of material	• Remover supplied in a single component form
	Packaging	• Remover supplied in a two 5l bottles for each piece

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ORDER DESCRIPTION

1. Object of the contract

The subject of the contract is Solvent in the amount of:

- Photoresist solvent – 1 piece, packaged into 5l bottle

2. Parametres

5.1 Detailed scope of the subject of the contract

Product name	Parameter	Specification
1. Photoresist solvent	Properties	• Low vapor pressure and suppression of particle formation in the resist • Can be used for edge bead removal • Density: 0.97 g/cm3 • Melting point: -66°C • Boiling point: 125°C • Flash point: 45°C • Vapour pressure 20°C: 5 hPa
	Form of material	• Solvent supplied in a single component form
	Packaging	• Solvent supplied in a single 5l bottle

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VIGO SYSTEM

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ORDER DESCRIPTION

1. Object of the contract

The subject of the contract is Negative Photoresists in the amount of:

- Negative photoresist with viscosity 115 CPS – 1 piece in 0.25l bottle
- Negative photoresist with viscosity diluted 1:0.50 – 2 µm grade in 0.25l bottle

2. Parametres

5.1 Detailed scope of the subject of the contract

Product name	Parameters	Specification
1. Negative photoresist	Properties	• Negative photoresist • Viscosity: 115CPS • Film thickness: 6 µm by single coat • Softbake: 110°C/120sec. • UV-sensitivity: Dose = 300 ± 50 mJ/cm²; Focus: 1 ± 0,5 µm • PEB: 120°C/60sec. • The resist sidewalls are very steep • Excellent adhesion, no underplating • Wide substrate compatibility: Cu, Au, Ti, NiFe
	Form of material	• Photoresist supplied in a single component form
	Packaging	• Photoresist supplied in a single 0.25 l bottle
2. Negative diluted photoresist	Properties	• Negative photoresist • Fotoresist from 1 point above, diluted 1: 0.50 – 2 µm grade
	Form of material	• Photoresist supplied in a single component form
	Packaging	• Photoresist supplied in a single 0.25 l bottle